

CSPESD304

4-Channel ESD Array in CSP

Product Description

The CSPESD304 is a quad ESD transient voltage suppression diode array. Each diode provides a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). These diodes safely dissipate ESD strikes of ± 15 kV, exceeding the maximum requirement of the IEC 61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the device provides protection for contact discharges to greater than ± 30 kV.

The CSPESD304 is particularly well-suited for portable electronics (e.g., cellular telephones, PDAs, notebook computers) because of its small package and low weight.

The CSPESD304 is available in a space-saving, low-profile Chip Scale Package with lead-free finishing.

Features

- Four Channels of ESD Protection
- ± 15 kV ESD Protection on each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- ± 30 kV ESD Protection on each Channel (HBM)
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum ESD Protection
- 5-Bump, 0.960 mm x 1.330 mm Footprint Chip Scale Package (CSP)
- These Devices are Pb-Free and are RoHS Compliant

Applications

- ESD Protection for Sensitive Electronic Equipment
- I/O Port and Keypad and Button Circuitry Protection for Portable Devices
- Can be Used for EMI Filtering when Combined with External Series Resistance
- Wireless Handsets
- Handheld PCs / PDAs
- MP3 Players
- Digital Camcorders
- Notebooks
- Desktop PCs



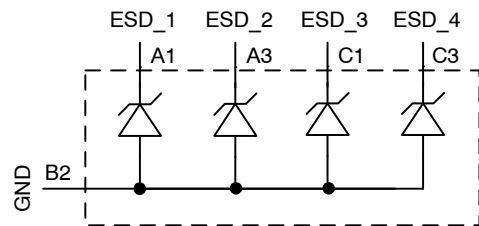
ON Semiconductor®

<http://onsemi.com>

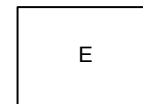


WLCSP5
CASE 567AY

ELECTRICAL SCHEMATIC



MARKING DIAGRAM



E = CSPESD304

ORDERING INFORMATION

Device	Package	Shipping†
CSPESD304	CSP-5 (Pb-Free)	3500/Tape & Reel

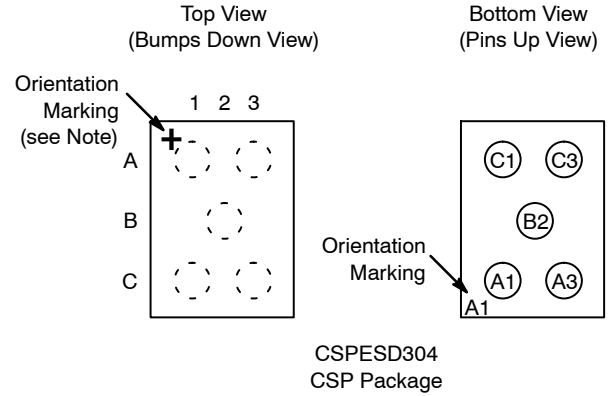
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CSPESED304

Table 1. PIN DESCRIPTIONS

5-bump CSP Package		
Pin	Name	Description
A1	ESD_1	ESD Channel 1
A3	ESD_2	ESD Channel 2
B2	GND	Device Ground
C1	ESD_3	ESD Channel 3
C3	ESD_4	ESD Channel 4

PACKAGE / PINOUT DIAGRAMS



Note: Lead-free devices are specified by using a "+" character for the top side orientation mark.

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
DC Package Power Rating	200	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{DIODE}	Diode Reverse Breakdown Voltage	$I_{DIODE} = 10 \mu A$	5.5			V
I_{LEAK}	Diode Leakage Current	$V_{IN} = 3.3 V, T_A = 25^\circ C$			100	nA
V_{SIG}	Signal Voltage Positive Clamp Negative Clamp	$I_{DIODE} = 10 mA$	5.6 -0.4	6.8 -0.8	9.0 -1.5	V
V_{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	(Note 2)	± 30 ± 15			kV
V_{CL}	Clamping Voltage during ESD Discharge MIL-STD-883 (Method 3015), 8 kV Positive Transients Negative Transients	(Note 2)		+15 -8		V
C_{DIODE}	Diode Capacitance	At 2.5 VDC Reverse Bias, 1 MHz, 30 mVAC	22	27	32	pF

- $T_A = -40$ to $+85^\circ C$ unless otherwise specified.
- ESD applied to input and output pins with respect to GND, one at a time.

CSPE3D304

PERFORMANCE INFORMATION

Diode Characteristics (nominal conditions unless specified otherwise)

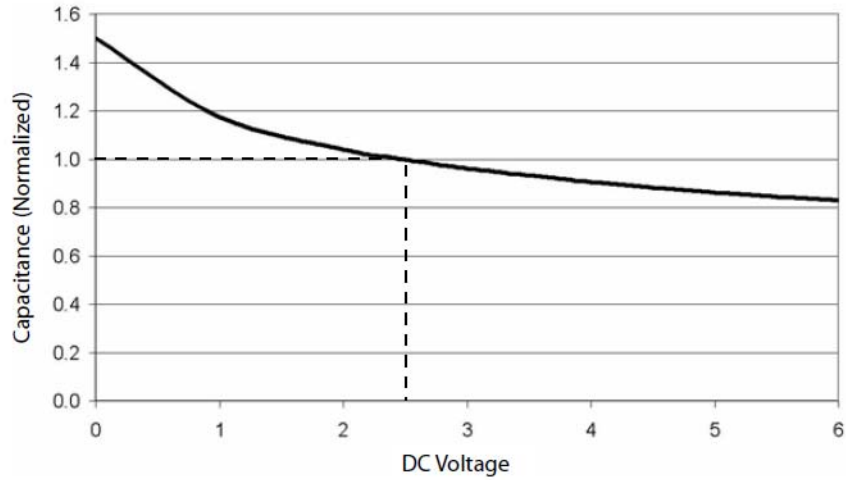


Figure 1. Typical Diode Capacitance vs. Input Voltage (normalized to 2.5 VDC)

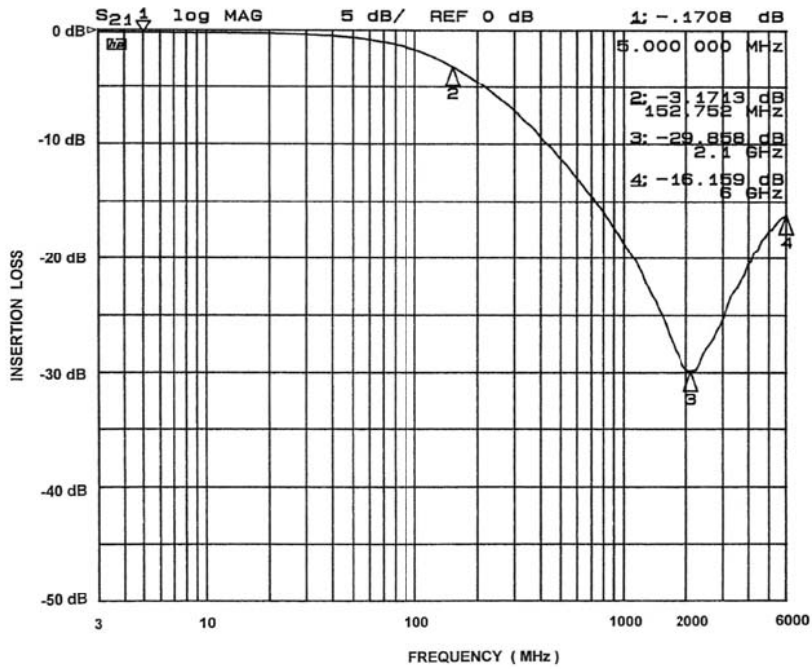


Figure 2. Frequency Response (single channel vs. GND, in 50 Ω system)

CSPE304

APPLICATION INFORMATION

Parameter	Value
Pad Size on PCB	0.240 mm
Pad Shape	Round
Pad Definition	Non-Solder Mask defined pads
Solder Mask Opening	0.290 mm Round
Solder Stencil Thickness	0.125 mm – 0.150 mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.300 mm Round
Solder Flux Ratio	50/50 by volume
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance – Edge To Corner Ball	±50 µm
Solder Ball Side Coplanarity	±20 µm
Maximum Dwell Time Above Liquidous	60 seconds
Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste	260°C

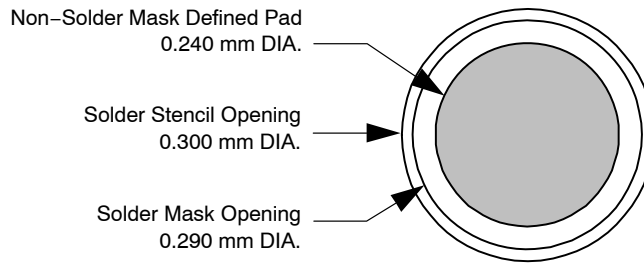


Figure 3. Recommended Non-Solder Mask Defined Pad Illustration

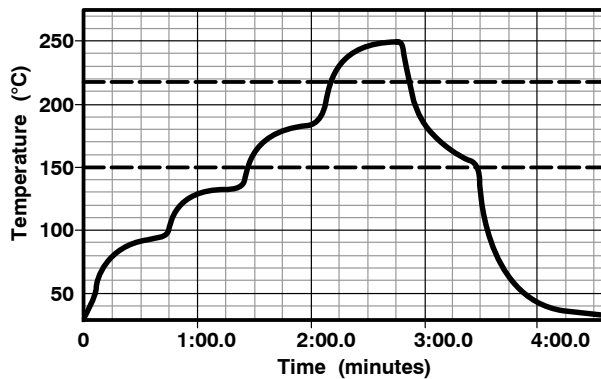


Figure 4. Lead-free (SnAgCu) Solder Ball Reflow Profile

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

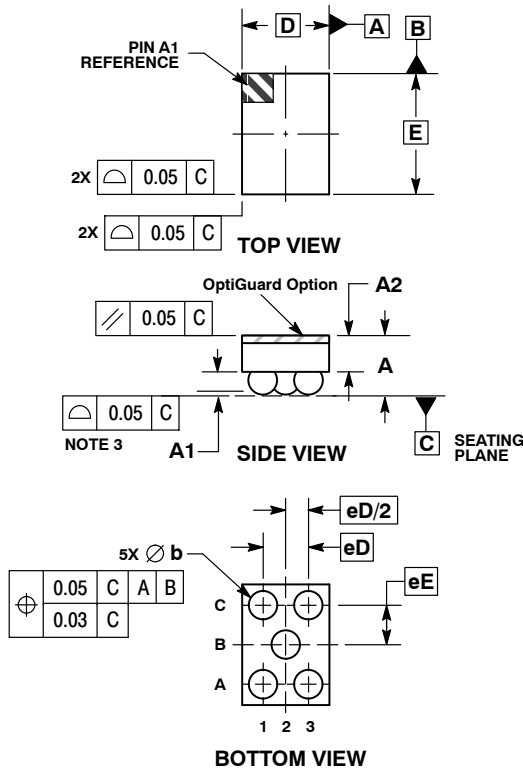
ON Semiconductor®



SCALE 4:1

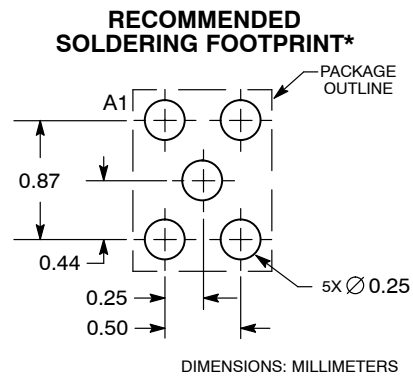
WLCSP5, 0.96x1.33
CASE 567AY-01
ISSUE O

DATE 26 JUL 2010



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.72
A1	0.21	0.27
A2	0.40 REF	
b	0.29	0.35
D	0.96 BSC	
E	1.33 BSC	
eD	0.50 BSC	
eE	0.435 BSC	



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON49808E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP5, 0.96X1.33	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales

